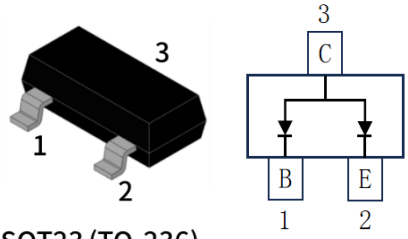
1SS181LDT1

SWITCHING DIODE

1. FEATURES

- Small package
- Low forward voltage
- Fast reverse recovery time
- Small total capacitane



SOT23 (TO-236)

2. Mechanical Data

- SOT-23 Small Outline Plastic Package.
- Tin plated leads, solderable per J-STD-002 and JESD22-B102.
- Marking:A3

3. ORDERING INFORMATION

Device	Min Pack	Inner Box	Outer Carton	Reel
1SS181LDT1	3000	45000	180000	7 inch

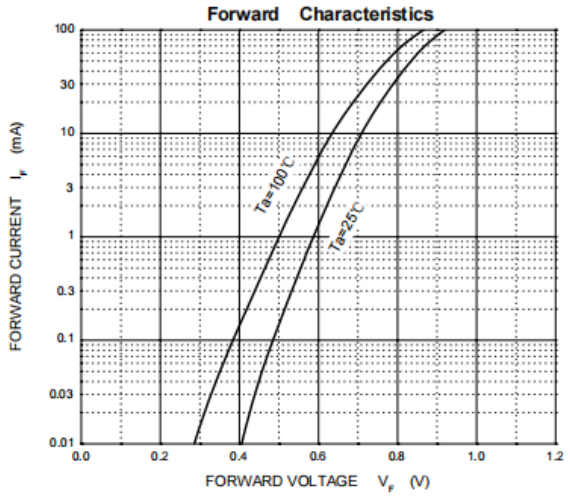
4. MAXIMUM RATINGS (Ta = 25°C)

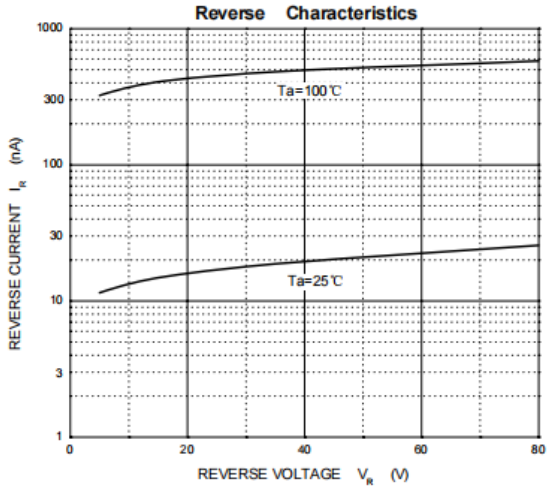
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	VRM	85	V
DC Blocking Voltage	VR	80	V
Forward Continous Current	IFM	300	mA
Power Dissipation	PD	350	mW
Non-Repetitive Peak Forward Surge Current @t=8.3ms	IFSM	2	A
Operation Junction and Storage Temperature Range	TJ, TSTG	-55-150	℃

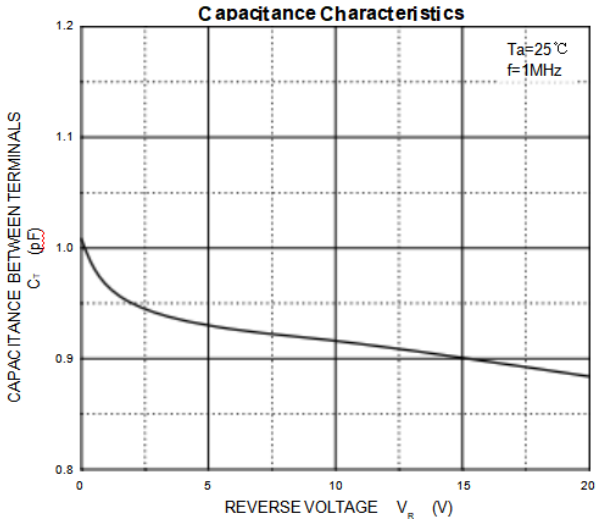
5. ELECTRICAL CHARACTERISTICS (Ta= 25°C unless otherwise specified)

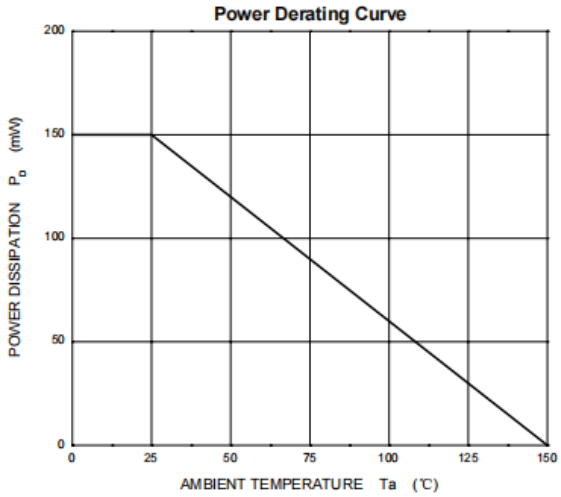
Parameter	Symbol	Condition	Min	TYP	Max	Unit
Reverse Breakdown Voltage	V(BR)	IR=0.1mA	80			V
Forward Voltage	VF	IF=1mA		0.61		V
		IF=10mA		0.74		V
		IF=100mA		0.92	1.2	V
Reverse Voltage Leakage Current	IR	VR=30V			0.1	μA
		VR=80V			0.5	μA
Capacitance between terminals	CT	VR=0, f=1MHZ		2.2	4	PF
Reverse recovery time	trr	IF=IR=10mA, RL=100Ω, IRR=0.1IR		1.6		ns

7.ELECTRICAL CHARACTERISTICS CURVES

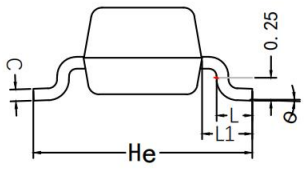


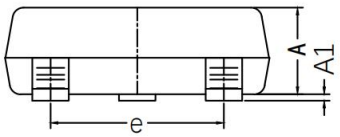


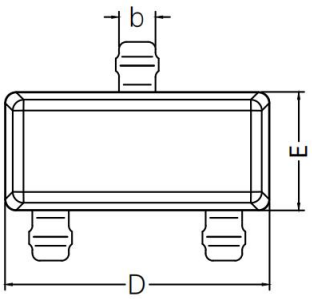




8.OUTLINE AND DIMENSIONS

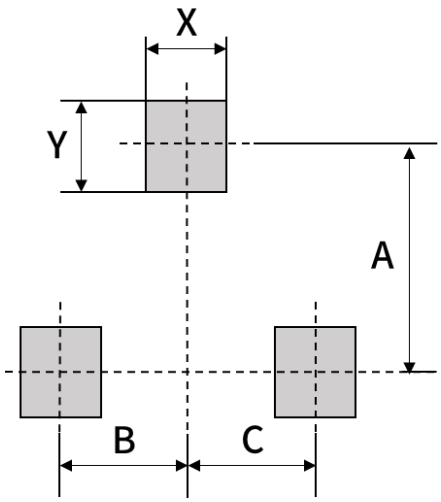






DIM	MIN	NOR	MAX
A	0.85	0.95	1.05
A1	0.01	0.06	0.10
b	0.36	0.44	0.52
c	0.09	0.13	0.18
D	2.80	2.90	3.10
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.40	0.50
L1	0.35	0.50	0.65
He	2.10	2.35	2.50
θ	0°	-	10°
All Dimensions in mm			

9. SUGGESTED PAD LAYOUT



SOT23		
DIM	mm	inch
A	2.00	0.079
B	0.95	0.037
C	0.95	0.037
X	0.80	0.031
Y	0.90	0.035

10. DISCLAIMER

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